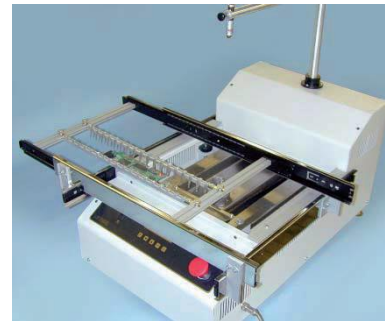
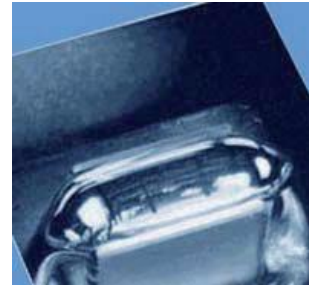


Manual Selective Soldering System- MS-10



Lead Free Capable



System Features

The ASI Manual Selective Soldering System can be used for the removal and replacement of through-hole components, connectors, etc. mounted on PC boards

- Microprocessor based, digital controller regulates:
 - solder temperature
 - wave height
 - solder flow duration
 - air "blow-through" duration
- 10 menu storage
- "Blow-thru" hot air nozzle option removes solder remaining in through-holes during rework process
- X, Y, & Z Universal Board Fixture option allows quick and easy board positioning over the wave
- Overhead locator laser light pinpoints position for centering component over the wave
- A large selection of nozzles for all component sizes is available. (14-20 pin DIP standard)
- Height adjustable stainless steel platform
- Easy to change bayonet mount nozzles for a variety of rework or selective soldering applications.

Manual Selective Soldering System- MS-10

Specifications	MS-10
Power	120 VAC, 60Hz, 15 A optional 220 VAC, 50/60 Hz, 8 A
Max solder temp	662°F (350°C)
Solder Capacity	50 lbs (23 Kg)
Compressed Air (MS-10A only)	60 PSI (4 bar)
Dimensions	16" x 26" x 17" (406 x 660 x 432mm)
Warm-up time	Approx. 30-45 min
Weight	30 lbs empty (13.5 kg), 80 lbs (36 Kg) with solder
MS-10	Solder Fountain
MS-10A	Solder Fountain with blow- through air nozzle
MS-UBF	Universal X, Y, & Z Board Option for board sizes up to 11" x 16.5" (280 x 420mm)

Device Type	Available Nozzle Sizes	Wave Nozzle	Air Nozzle
14-20 pin DIP	1.00" x 0.50" (25 x 13mm)	WN-10	AN-10
24-28 pin DIP	1.50" x 0.75" (38 x 19mm)	WN-20	AN-20
30-48 pin DIP	2.50" x 0.75" (64 x 19mm)	WN-30	AN-30
PGA	1.00" x 1.00" (25 x 25mm)	WN-40	AN-40
PGA	1.50" x 1.50" (38 x 38mm)	WN-50	AN-50
PGA	2.00" x 2.00" (50 x 50mm)	WN-60	AN-60
Flat connectors	2.75" x 0.35" (70 x 9mm)	WN-70	AN-70
Large connectors	4.00" x 0.75" (102 x 19mm)	WN-80	AN-80
Custom nozzles available	(5 in ² max., e.g. 1.25" x 4")		